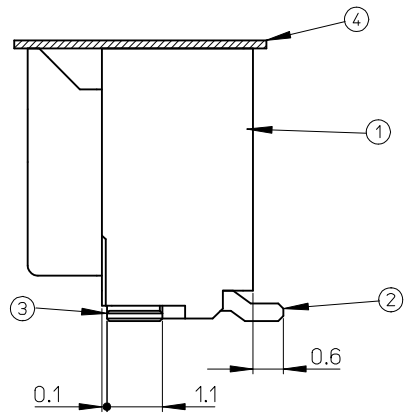
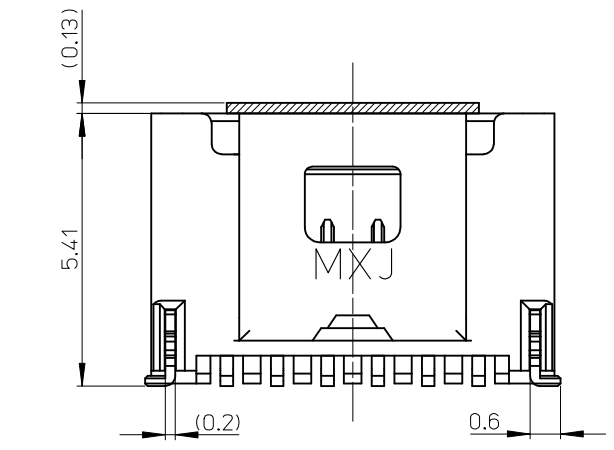


参考パターンレイアウト
 RECOMMENDED PATTERN DIM. (REF)
 SCALE:5:1 (メタルマスク厚:0.12mm)



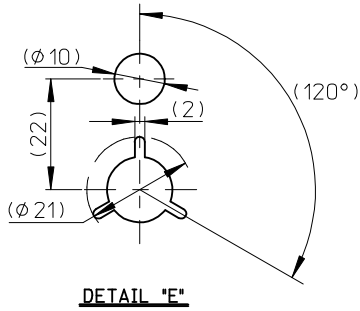
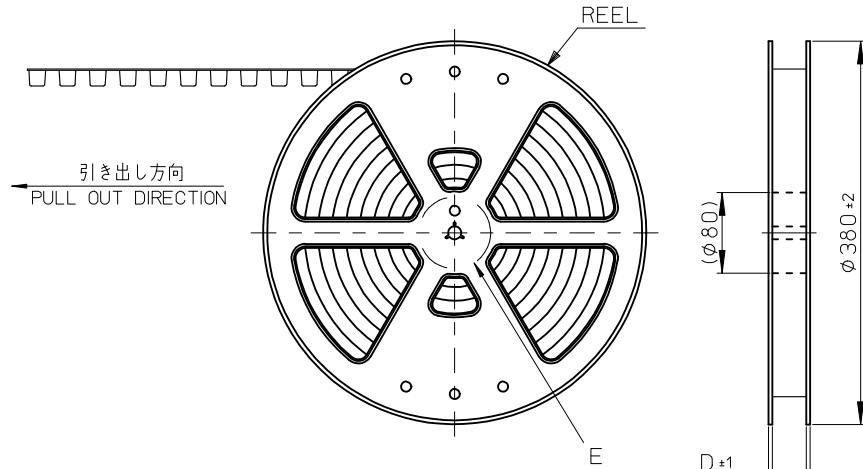
番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	ポリアミド UL94V-0 色:ナチュラル POLYAMIDE UL94V-0, COLOR: NATURAL
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 部分金メッキ: 0.1μmMIN. SEPARATED GOLD PLATING ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
④	カバーテープ COVER TAPE	ポリイミドテープ POLYIMIDE TAPE

※対応可能な極数は、別途お問い合わせ下さい。

14.0	17.0	504449-1507	15
13.0	16.0	504449-1407	14
12.0	15.0	504449-1307	13
11.0	14.0	504449-1207	12
10.0	13.0	504449-1107	11
9.0	12.0	504449-1007	10
8.0	11.0	504449-0907	9
7.0	10.0	504449-0807	8
6.0	9.0	504449-0707	7
5.0	8.0	504449-0607	6
B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	極数 CKT.

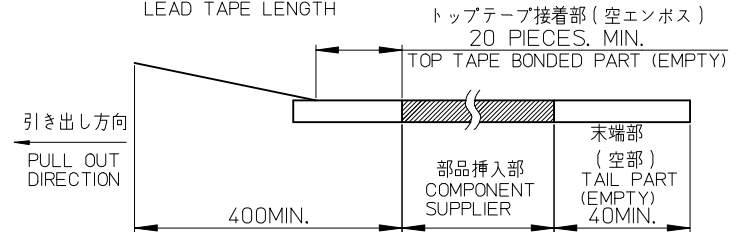
- NOTES.
1. 嵌合相手: 501330-****
MATE WITH: 501330-****
 2. ソルダーピン及びネイル平坦度は、0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
 3. 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
 4. 2~5極は、SD-504449-001を参照下さい。
REFER TO SD-504449-001 ABOUT 2-5CKT.
 5. ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.

RELEASED EC NO: J2012-1436 DRWN: KWASHIO 2012/12/13 CHKD: KASAKAWA 2012/12/14 APPR: YOITO 2012/12/21 REV: O	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED) 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		DRAWN BY KWASHIO	DATE 2012/12/13	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) 6-15CKT		
		CHECKED BY YOITO	DATE 2012/12/21	molex		
		APPROVED BY YOITO	DATE 2012/12/21	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-504449-002	SHEET NO. 1 OF 1
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



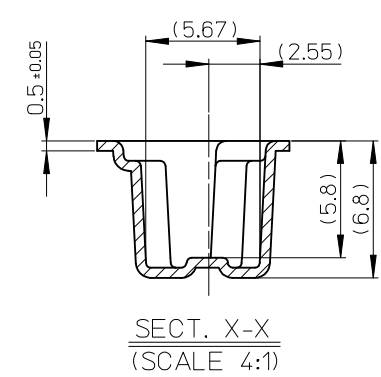
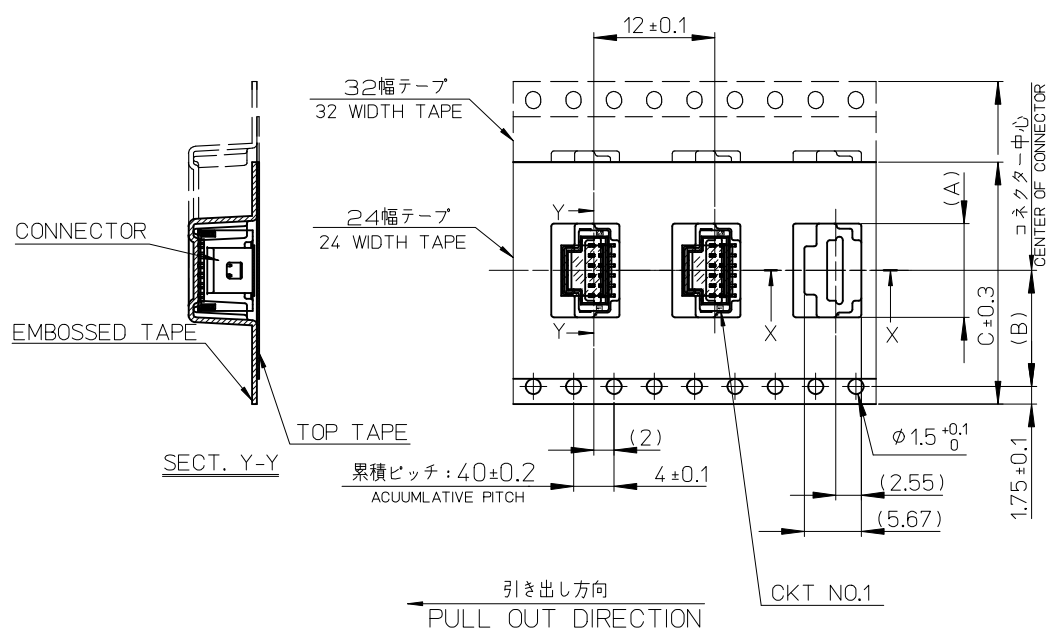
NOTES.

- 製品詳細寸法については製品単体図面を参照ください。
ABOUT DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量：1100個/リール
NUMBER OF CONNECTORS：1100PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- 材料
MATERIAL
キャリアテープ：ポリプロピレン
CARRIER TAPE：POLYPROPYLENE
トップテープ：PET、PE、REF
TOP TAPE
リール：ポリスチレン (リサイクル材を含む)
REEL：POLYSTYLENE (RECYCLE MATERIAL CONTAINED)
- ELV 及び RoHS適合品
ELV AND RoHS COMPLIANT.

RELEASED EC NO: J2012-1436 DRWN: KWASHIO 2012/12/13 CHKD: KASAKAWA 2012/12/14 APPR: YOITO 2012/12/21	DESCRIPTION REV 0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY KWASHIO	DATE 2012/12/13	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG				
		10 OVER 30 UNDER	±0.25	CHECKED BY	DATE	molex DOCUMENT NO. SD-504449-004 SHEET NO. 1 OF 2				
		30 OVER	±0.3	APPROVED BY YOITO	DATE 2012/12/21					
		ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 2				
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



37.4	33.4	32	14.2	18.3	504449-1507	15	
				17.3	504449-1407	14	
				16.3	504449-1307	13	
29.4	25.4	24	11.5	15.3	504449-1207	12	
				14.3	504449-1107	11	
				13.3	504449-1007	10	
				12.3	504449-0907	9	
				11.3	504449-0807	8	
				10.3	504449-0707	7	
E	D	C	(B)	(A)	9.3	504449-0607	6
					EMBOSSSED PACKAGE 極数		
オーダー番号 ORDER NO.						CKT.	

CONNECTOR SERIES No. 504449-***9

SEE SHEET1 EC NO: J2012-1436 DRWN: KWASHIO 2012/12/13 CHKD: KASAKAWA 2012/12/14 APPR: YOITO 2012/12/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY KWASHIO	DATE 2012/12/13	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG		
	10 OVER 30 UNDER	±0.25	CHECKED BY	DATE	APPROVED BY YOITO 2012/12/21		
	30 OVER	±0.3	MATERIAL NO.		DOCUMENT NO. SD-504449-004		
	ANGULAR ±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SHEET NO. 2 OF 2	